

National Aeronautics and Space Administration



# Power Hibernation to Survive the Lunar Night

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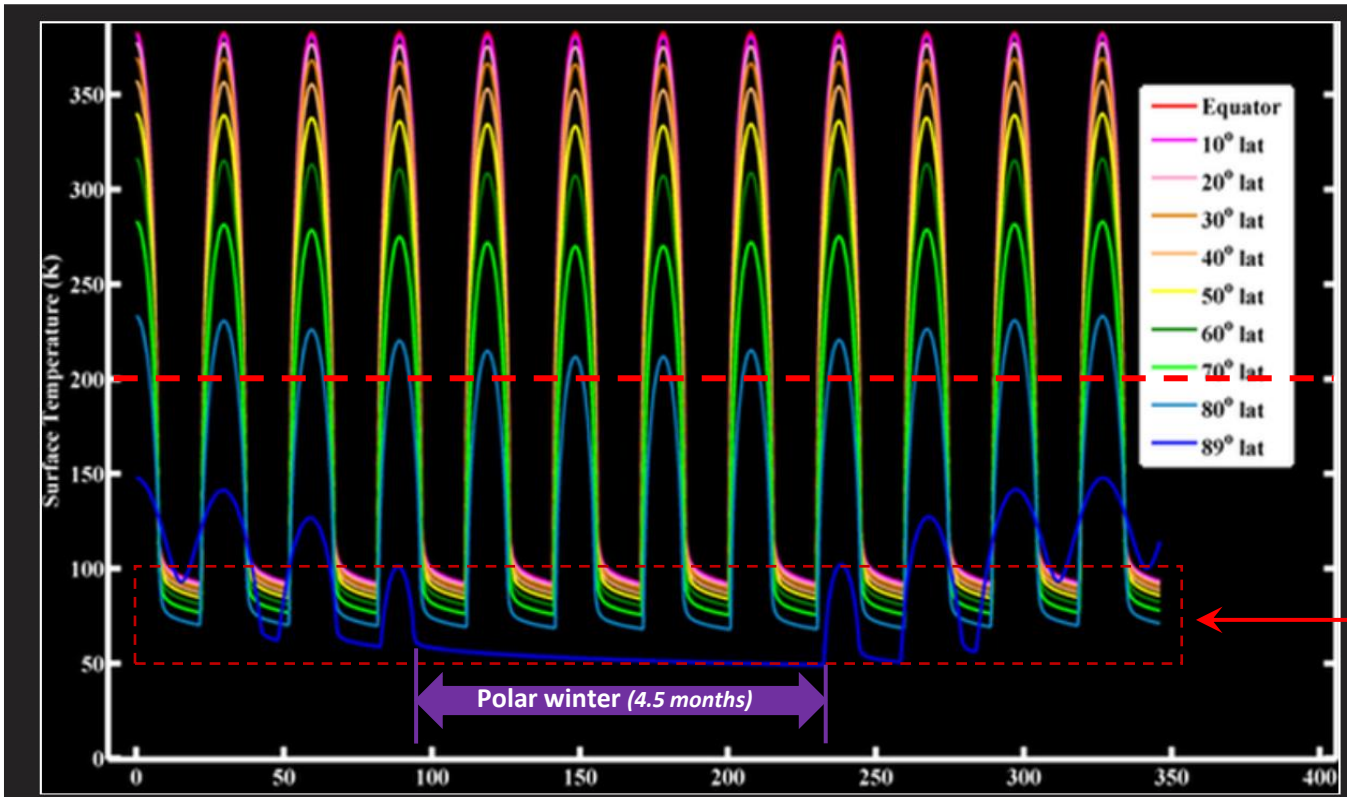
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# Background

## The Extreme Lunar Environment



### LRO DIVINER: Lunar Day/Night Temperature Range by Latitude



- Day: 100-400 K highs based on latitude
- Night: 50-100 K lows for *all* latitudes
  - Duration (non-polar): ~354 hrs (~15 Earth days)
  - Duration (polar): winter sun below horizon for ~4.5 months

← Li-ion battery  
approx. freeze  
temperature

← Lunar night is  
extremely cold  
*everywhere*

Thermal model calculations of monthly and annual lunar surface temperature variations at various latitudes

# Background Lunar Power Systems



- **Power System Survivability**

- Radioisotope systems provide nighttime heat and power, but are regulated and costly
- Traditional solar panel and small battery systems *cannot* survive reliably
- Large batteries providing sufficient heat are mass-prohibitive due to night duration

- **Lightweight Battery Solution**

- Surveyor (1966-1968) used silver-zinc batteries
  - Not designed to survive night conditions, but a few experienced unexpected battery activity after returning to daylight
- Recent research shows that lithium-ion (Li-ion) batteries can be safely frozen and thawed without apparent performance degradation
  - Relies on cryogenically tolerant and operable electronics to properly manage revival

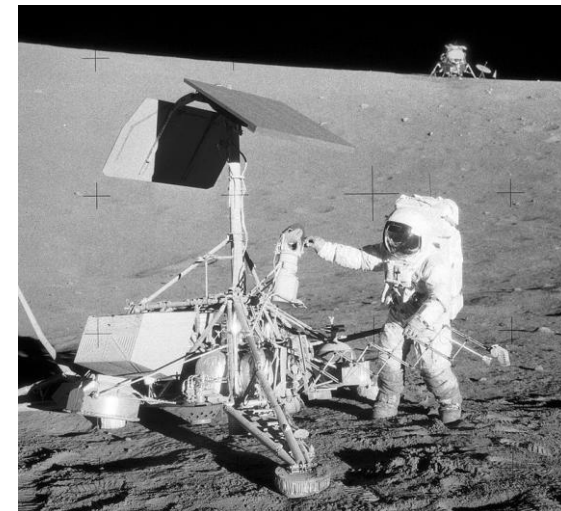


Image Credit: NASA

# Overview

## Proposed Survival Strategy



- **Lunar Power Hibernation**

- Extends capabilities and duration of lunar missions
- Reduces dependency on radioisotopes, pre-established infrastructure
- Success depends on:
  - Cryo-tolerant Li-ion batteries
  - Cryo-tolerant electronics to operate reliably in nominal conditions (after dawn)
  - Cryo-operable electronics to perform cold start and safely restore power

- **Hibernation Applications**

- Commercial Lunar Payload Services (CLPS)
  - Landers currently provide only a single lunar day of operation
- Robotic elements of the Artemis Program
- Lunar in-situ resource utilization (ISRU) systems
- Survival and recovery options in contingency situations



- **Cryo-Tolerant**

- Required for all spacecraft electronics (power, avionics, comm)
- Must passively withstand thermal environment down to 50 K without damage
- Can depend on manufacturing processes and materials/packaging

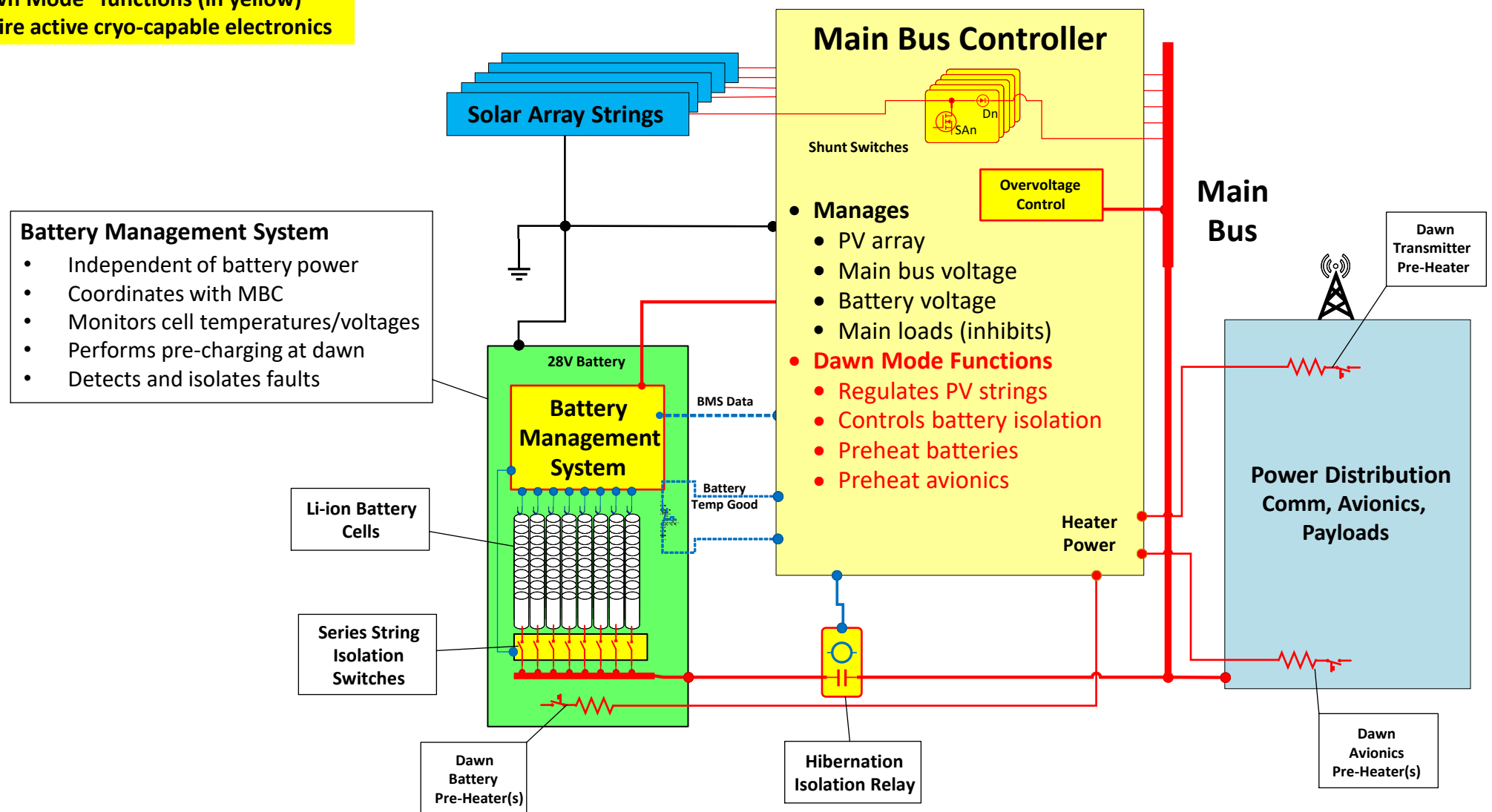
- **Cryo-Operable**

- Required for hibernation electronics that restore power at lunar dawn
- Must start up and operate in 50-100 K lunar dawn
- Contingent on device properties and stability of interactions



# Overview Hibernation Power Architecture

“Dawn Mode” functions (in yellow)  
require active cryo-capable electronics



# Overview Sample Revival Sequence



## Key

*Cryo-tolerant*

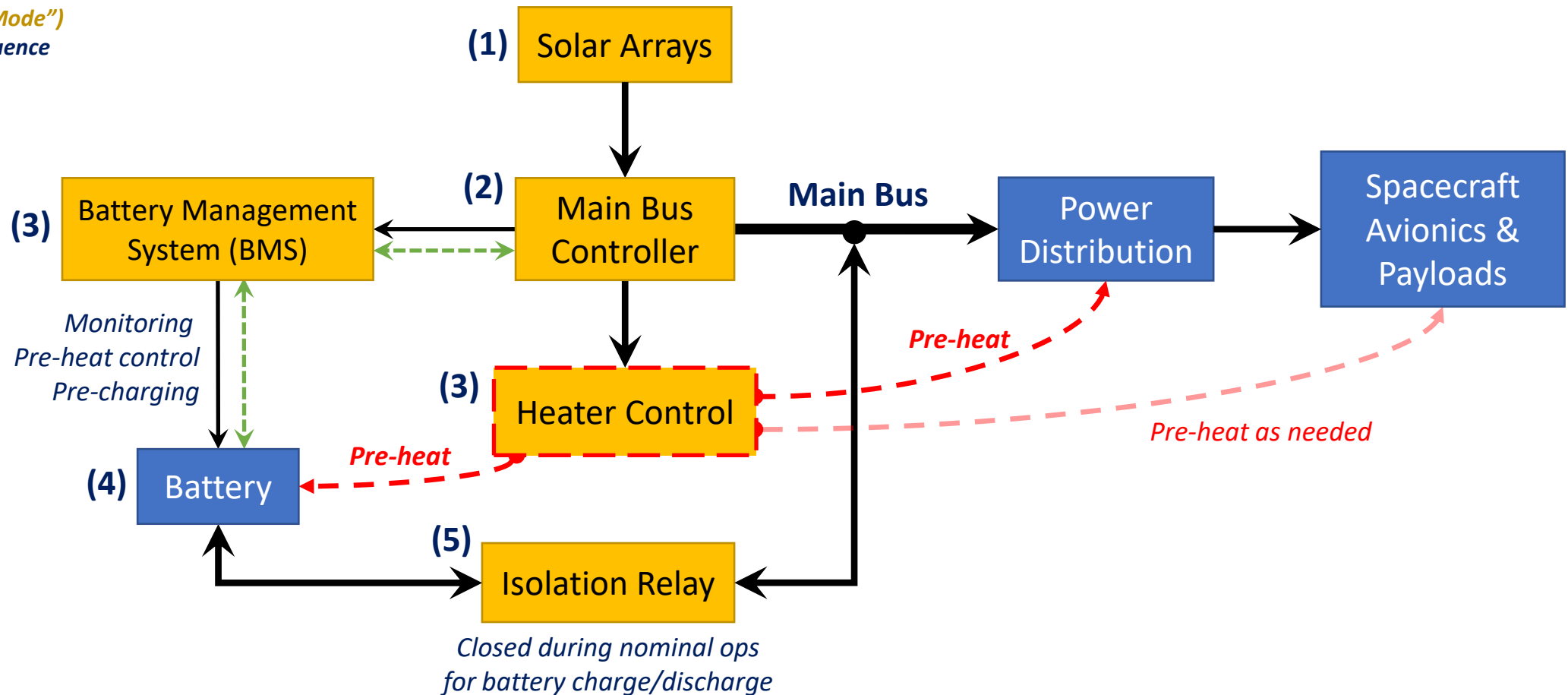
*Cryo-operable ("Dawn Mode")*

*(#) – Dawn start-up sequence*

→ Power

→ Thermal

→ C&DH





# Batteries

## Lithium-Ion Cell Investigation at NASA GRC



- **Initial Tests**

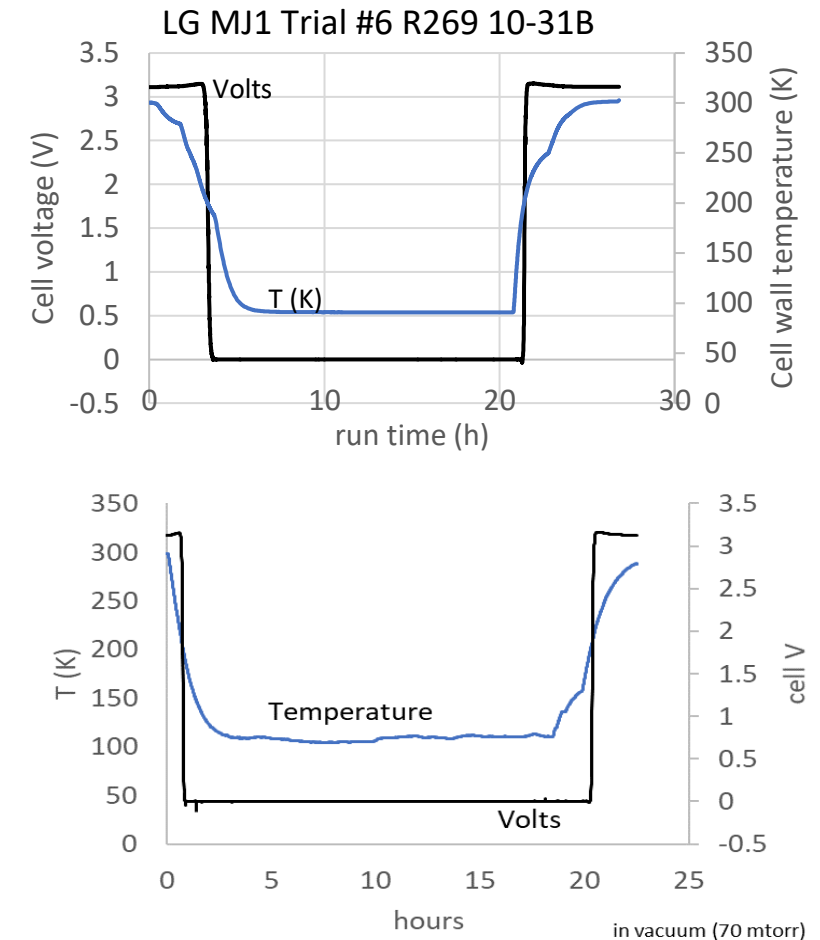
- Performed at 1 atmosphere
- LN2 vapor chilled to 80 K (-193 °C)

- **Refined Tests**

- Performed in vacuum (70 mTorr)
- Cryocooler chilled to 100 K (-173 °C)

- **18650 Cell Results**

- Near 200 K (-70 °C), voltage drops to 0 V
- Above 200 K, voltage and capacity recover
- No apparent degradation



Figures courtesy of W. Bennett / NASA GRC



# Electronics Choosing Components for Cryo-Operability



Device		Advantages	Challenges
Semiconductors	Diodes (PN, Schottky)	<ul style="list-style-type: none"> <li>Can be operational at lunar temperatures with proper design and part selection</li> </ul>	<ul style="list-style-type: none"> <li>Forward voltage generally increases at cryo temperatures</li> <li>On-resistance increases below 100 K (except for GaN Schottky)</li> </ul>
	Bipolar Junction Transistor (BJT)	<ul style="list-style-type: none"> <li>Increased gain at cryogenic temperatures (SiC)</li> </ul>	<ul style="list-style-type: none"> <li>DC gain decreases dramatically with temperature (Si)</li> <li>Likely unsuitable for use due to carrier freeze-out (Si)</li> </ul>
	Junction-Gate FET (JFET)	<ul style="list-style-type: none"> <li>Normally-on JFET performance at lunar night temperatures similar to that at room temperature (SiC)</li> </ul>	<ul style="list-style-type: none"> <li>Carrier freeze-out increases on-resistance as temperatures decrease past ~200 K</li> </ul>
	Metal Oxide Semiconductor FET (MOSFET)	<ul style="list-style-type: none"> <li>On-resistance decreases w/ low temperature until ~77 K (Si)</li> <li>Switching time improves w/ low temperature (Si)</li> </ul>	<ul style="list-style-type: none"> <li>Threshold voltage increases; breakdown voltage decreases (Si)</li> <li>Enhancement-mode SiC unsuitable – extreme carrier freeze-out</li> </ul>
	High-Electron Mobility Transistor (HEMT)	<ul style="list-style-type: none"> <li>On-resistance/switching time improves w/ low temperature; breakdown/threshold voltage doesn't change (GaN)</li> </ul>	
	Insulated-Gate Bipolar Transistor (IGBT)	<ul style="list-style-type: none"> <li>Improved switching speed, forward voltage, and transconductance</li> </ul>	<ul style="list-style-type: none"> <li>Breakdown voltage decreases</li> <li>Threshold voltage slightly increases</li> </ul>
Passives	Resistors	<ul style="list-style-type: none"> <li>Wire-wound and metal film have low TCRs (temp coefficients of resistance)</li> </ul>	<ul style="list-style-type: none"> <li>Thick-film and carbon are greatly affected by temperature</li> </ul>
	Ceramic Capacitors	<ul style="list-style-type: none"> <li>Class I (paraelectrics): Good capacitance stability over temperature</li> </ul>	<ul style="list-style-type: none"> <li>Class II (ferroelectrics): Higher variability over temperature ranges</li> </ul>
	Electrolytic Capacitors	<ul style="list-style-type: none"> <li>Solid tantalum electrolytics will operate marginally</li> </ul>	<ul style="list-style-type: none"> <li>Aluminum electrolytic (liquid): Electrolyte freezes at cryo temperatures</li> <li>Tantalum electrolytic (solid): Higher dissipation factor and ESR, lowered capacitance at higher frequencies</li> </ul>
	Inductors	<ul style="list-style-type: none"> <li>Air core inductors likely have little change in properties due to no core material</li> </ul>	<ul style="list-style-type: none"> <li>Solid core inductors require special core material tailored for low losses at cryo temperatures</li> </ul>



- **Lunar Power Hibernation Architecture**
  - Reduces dependency on other prohibitive forms of power delivery
  - Enables longer-term missions across multiple lunar cycles
  - Can be implemented on existing designs at low cost and mass
- **Lithium-ion Battery Management**
  - Proven to be capable of freezing and thawing w/ little-to-no loss of performance
  - BMS should be implemented to control warming
- **Electronics Design Considerations**
  - Minimize size of boards and part footprints, match CTE, avoid tin
  - Most semiconductors can operate at cryogenic temperatures (50-100 K)
    - Carrier freeze-out and electron tunneling may be a concern
  - Solutions exist for most implementations of passive devices



# Future Work

- Characterize safe Li-ion hibernation management
- Continue review of academic works
- If possible, build parts model library for simulation
- Test cryogenic operation of discrete parts
- Develop prototype cryo-circuit based on guidelines
- Conduct circuit-level testing with batteries and solar cells
  
- **Seeking collaboration opportunities!**

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# Acronyms and Abbreviations

- |        |                                   |          |                                       |
|--------|-----------------------------------|----------|---------------------------------------|
| • BJT  | Bipolar Junction Transistor       | • IGBT   | Insulated-Gate Bipolar Transistor     |
| • BMS  | Battery Management System         | • ISRU   | In Situ Resource Utilization          |
| • C&DH | Command and Data Handling         | • JFET   | Junction-Gate FET                     |
| • CLPS | Commercial Lunar Payload Services | • Li-ion | Lithium-ion                           |
| • Comm | Communications                    | • LRO    | Lunar Reconnaissance Orbiter          |
| • Cryo | Cryogenic                         | • MBC    | Main Bus Controller                   |
| • CTE  | Coefficient of Thermal Expansion  | • MOSFET | Metal Oxide Semiconductor FET         |
| • ESR  | Equivalent Series Resistance      | • NEPP   | NASA Electronic Parts and Packaging   |
| • FET  | Field-Effect Transistor           | • PCB    | Printed Circuit Board                 |
| • FRP  | Fiberglass-Reinforced Plastic     | • TCR    | Temperature Coefficient of Resistance |
| • GRC  | Glenn Research Center             | • Temp   | Temperature                           |
| • HEMT | High-Electron Mobility Transistor |          |                                       |



# Power Hibernation to Survive the Lunar Night

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